



**EVALUATION TEST PROGRAMME FOR DISCRETE  
NON-MICROWAVE SEMICONDUCTORS**

**ESCC Basic Specification No. 2265000**

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## 1 **PURPOSE**

The purpose of this specification is to establish the procedure to be followed in the evaluation of component capabilities as required for space applications and thereby to anticipate, as far as possible, component behaviour during qualification testing. Therefore, the aim of such testing shall be to overstress specific characteristics of the component concerned with a view to the detection of possible failure modes. Additionally, a detailed destructive physical analysis shall be performed to detect any design and construction defects which may affect the reliability of the component and to facilitate failure analysis activities. The evaluation shall also include a check of the susceptibility of the component to ESD damage.

## 2 **APPLICABLE DOCUMENTS**

The following documents form part of, and shall be read in conjunction with, this specification.

### 2.1 **ESCC SPECIFICATIONS**

No. [5000](#), Discrete Semiconductor Components.

No. [20400](#), Internal Visual Inspection.

No. [20500](#), External Visual Inspection.

No. [20900](#), Radiographic Inspection.

No. [22900](#), Total Dose Steady-State Irradiation Test Method.

No. [23800](#), Electrostatic Discharge Sensitivity Test Method.

Unless otherwise stated herein, reference within the text of this specification to "the Detail Specification" shall mean the relevant ESCC Detail Specification.

### 2.2 **OTHER (REFERENCE) DOCUMENTS**

IEC Publication No. 60068, Basic Environmental Testing Procedures.

[MIL-STD-750](#), Test Methods and Procedures for Semiconductor Devices.

[MIL-STD-883](#), Test Methods and Procedures for Microelectronics.

ECSS-Q-ST-70-02, A Thermal Vacuum Test for the Screening of Space Materials.

## 3 **PROCEDURE**

Standard components shall be selected from a homogeneous lot at the Manufacturer to be evaluated. These components shall not have been submitted to any screening or burn-in, but must have been manufactured in conformity with high reliability practice and an established Process Identification Document (PID) or an identifiable process which shall form the basis for the PID.

The tests specified in the programme shall be performed in the sequence shown in Chart I. All results shall be recorded and failed components submitted to a failure analysis. Probable failure modes and mechanisms shall be determined.

The evaluation testing programme shall be performed, under the supervision of the ESCC Executive, by the Manufacturer or at a test laboratory approved by the ESCC Executive.

## **4 TEST PROGRAMME SEQUENCE AND SAMPLE DISTRIBUTION**

### **4.1 SELECTION OF COMPONENTS FOR EVALUATION TESTING**

The number of components to be selected for evaluation testing shall depend on whether a single component type or a family of parts is evaluated and the number of component types chosen to represent the family.

Not less than 93 to 108 samples (see Para. 7.3.2.1 and Chart I) shall be used for each test programme.

The component types chosen to represent a family shall cover the range of components to be evaluated and be representative of the different package and pin configurations under consideration. They shall also be the most suitable for highlighting those characteristics and parameters that are pertinent to an investigation into failure modes and weaknesses.

The samples shall be as specified by, or as agreed with, the ESCC Executive.

The above mentioned quantity shall be submitted to the full evaluation procedure whenever a new technology has been applied to the components concerned, where there is insufficient experience in their production.

### **4.2 DETAIL SPECIFICATIONS**

Should a Detail Specification for the device(s) to be evaluated not exist, the Manufacturer shall prepare such a document(s) in accordance with the established ESCC format and submit it to the ESCC Executive for provisional approval. This shall then serve as a basis for the ordering and testing of the relevant components.

### **4.3 INSPECTION RIGHTS**

The ESCC Executive reserves the right to inspect at any time the components processed for evaluation purposes. The Manufacturer shall notify the ESCC Executive at least three working days in advance of the date of internal visual inspection (but see Para. 4.4).

### **4.4 CONTROL DURING FABRICATION**

The components shall be produced as defined in Para. 3 of this specification. Internal visual inspections shall be performed on the lot to be tested to the extent that this forms part of the Manufacturer's standard procedures. Progress of the components shall be observed closely and recorded together with an analysis of any reject. A chart showing the numbers in/out and failure cause for each fabrication stage shall be submitted to the ESCC Executive.

## 5 INSPECTION

### 5.1 GENERAL

The components shall be checked to verify their suitability for the Evaluation Test Programme. Defects or deviations from the established ESCC requirements may invalidate the evaluation. For each measurement or inspection performed, the results shall be summarised in terms of quantity tested, quantity passed and quantity rejected. If devices are rejected, the reason shall be clearly identified.

### 5.2 DIMENSIONS (100%)

All devices shall be inspected (go-no-go) in accordance with Physical Dimensions and Terminal Identification in the Detail Specification. Where gauges exist for performance of measurements, these may be used. For packages with a high pin count, the measurements may be performed using a sampling scheme which shall be approved by the ESCC Executive. Rejected components shall be replaced.

### 5.3 WEIGHT (100%)

All devices shall be weighed. Any devices that exceed the weight defined in the Detail Specification shall be rejected and replaced.

### 5.4 ELECTRICAL MEASUREMENTS (100%)

These measurements shall be performed (go-no-go) in accordance with Room Temperature Electrical Measurements in the Detail Specification at an ambient temperature of  $+22 \pm 3^{\circ}\text{C}$ . Rejected components shall be replaced.

### 5.5 EXTERNAL VISUAL INSPECTION (100%)

All devices shall be inspected in accordance with ESCC Basic Specification No. [20500](#). Rejected components shall be replaced.

### 5.6 PARTICLE IMPACT NOISE DETECTION (PIND) (100%)

#### (a) Applicability

This test is only applicable to devices with a cavity.

#### (b) Procedure

All devices shall be tested in accordance with the requirements defined in ESCC Generic Specification No. [5000](#). Rejected components shall be replaced.

### 5.7 RADIOGRAPHIC INSPECTION (100%)

All devices shall be inspected in accordance with ESCC Basic Specification No. [20900](#). Additional axes to those specified in the relevant ancillary specification of ESCC Basic Specification No. [20900](#) may be radiographed if, by so doing, it is possible to observe any faults. Rejected components shall be replaced.

## 5.8 HERMETICITY (100%)

### 5.8.1 Penetrant Dye Test

- (a) Applicability  
This test is only applicable to glass cavity devices.
- (b) Procedure  
[MIL-STD-750 Method 1071](#), Test condition 'E'. Rejected components shall be replaced.

### 5.8.2 Seal Test

- (a) Applicability  
This test is not applicable to devices without a cavity.
- (b) Procedure  
Fine and gross leak tests shall be performed on all components in accordance with the requirements defined in ESCC Generic Specification No. [5000](#). Rejected components shall be replaced.

## 5.9 MARKING AND SERIALISATION (100%)

All components shall be marked and serialised in accordance with the standard procedures of the Manufacturer concerned.

## 5.10 MATERIALS AND FINISHES

All non-metallic materials and finishes, that are not within a hermetically sealed enclosure, of the components specified herein shall be tested in accordance with ECSS-Q-ST-70-02 to verify its outgassing requirements, unless relevant data is available.

## 5.11 COMPLETION OF INSPECTION

The completion of inspection shall result in a batch of components that have been verified as to their suitability for the Evaluation Test Programme, i.e. each component has satisfied the requirements of Paras. 5.2 to 5.10 inclusive.

## 6 INITIAL ELECTRICAL MEASUREMENTS (100% READ AND RECORD)

These measurements shall be made according to the Room, High and Low Temperatures Electrical Measurements Paras. in the Detail Specification. All characteristics shall be recorded against serial numbers.

## 7 EVALUATION TEST PROGRAMME

### 7.1 GENERAL

The evaluation tests shall be performed as specified in Chart I. The components shall be randomly divided into three groups and their associated subgroups in the proportions indicated in Chart I. When a family of components is under investigation, the variations within that family must be represented in each group/subgroup. The Subgroup 2A tests shall be completed and the results analysed before the Subgroup 3B tests are commenced.

All failed components shall be analysed. The depth of analysis shall depend upon the circumstances in which failure occurred and upon whether useful information may be gained. As a minimum, the failure mode shall be determined in each case. Components not failing catastrophically, i.e. those displaying out-of-tolerance electrical parameters, shall not be removed from the test sequence but monitored to observe degradation trends.

### 7.2 GROUP 1 - CONTROL GROUP

This group shall be retained for comparison purposes. Whenever electrical measurements are made on any devices under test, these devices shall also be measured.

### 7.3 GROUP 2 - DESTRUCTIVE TESTS

#### 7.3.1 General

This group shall be randomly divided into five subgroups in the proportions indicated in Chart I.

#### 7.3.2 Subgroup 2A - Step-Stress Tests

##### 7.3.2.1 *General*

When considered relevant to the component type and technology being evaluated, specific step-stress tests shall be performed in accordance with the following requirements. For each of these tests, Temperature Step-Stress (see Para. 7.3.2.4), Power Step-Stress (see Para. 7.3.2.5) and Intermittent Operating Life (see Para. 7.3.2.6), the Manufacturer shall demonstrate whether it is or is not applicable to the evaluation test programme in question. The applicability of each test shall be agreed with the ESCC Executive.

Subgroup 2A shall be randomly divided into upto three further subgroups in the proportions indicated in Chart I.

##### 7.3.2.2 *Determination of Thermal Resistance/Conductivity*

[MIL-STD-750, Method 31xx](#), as applicable.

##### 7.3.2.3 *Parameters to be measured during Step-Stress Tests*

During step-stress tests, electrical measurements shall be made in accordance with Parameter Drift Values in the Detail Specification. If parameter drift values are not specified in the Detail Specification, then the parameters to be measured shall be selected from Room Temperature Electrical Measurements in the Detail Specification. In the case of doubt as to the applicability of any given parameter, the parameter shall be measured. At the termination of the step-stress sequences, any surviving devices shall have their thermal resistance/conductivity measured as specified in Para. 7.3.2.2.

#### 7.3.2.4 *Subgroup 2A(i) - Temperature Step-Stress Test*

When applicable, the tests in this subgroup shall be performed as specified in Chart II. Electrical measurements shall be made as defined in Para. 7.3.2.3 above. The starting temperature (which will be no higher than the maximum operating temperature as defined in the Detail Specification) and the temperature steps (with a maximum step of +25°C) to be employed will be decided by the ESCC Executive.

This step-stress sequence shall be terminated when 50% (rounded up) of the samples have been destroyed, unless practical reasons prevent this.

#### 7.3.2.5 *Subgroup 2A(ii) - Power Step-Stress Test*

##### (a) *Applicability*

This test is only applicable to devices where operation in circuits requiring transfer and dissipation of significant and/or varying levels of power is an intended feature of their design.

##### (b) *Procedure*

When applicable, the tests in this subgroup shall be performed as specified in Chart III. Electrical measurements shall be made as defined in Para. 7.3.2.3 above. The starting power (which will be no higher than the maximum input power as defined in the Detail Specification) and the power steps (with a maximum step of +20%) to be employed will be decided by the ESCC Executive.

This step-stress sequence shall be terminated when 50% (rounded up) of the samples have been destroyed, unless practical reasons prevent this.

#### 7.3.2.6 *Subgroup 2A(iii) - Intermittent Operating Life Test*

When applicable, an Intermittent Operating Life test shall be performed in accordance with [MIL-STD-750 Test Method 1037](#) or [MIL-STD-750 Test Method 1042](#) Condition D (as applicable).

Components shall be tested until failure or up to 10000 cycles, whichever occurs first.

#### 7.3.2.7 *Analysis of Subgroup 2A*

The analysis of Subgroup 2A shall be presented to the ESCC Executive in a graphical form, supported by the actual results, as follows:

- The number of functional failures shall be plotted against each temperature or power level (if applicable) applied. The cumulative failure rate shall also be plotted.
- The parameters (as defined in Para. 7.3.2.3 above) shall be monitored, recorded and plotted against time for each temperature or power level (if applicable) as appropriate.
- The average drift of the parameters at each temperature or power level applied shall be plotted against temperature or power (if applicable) as appropriate.

The analysis of the results of Subgroup 2A(i), (ii) and (iii) (as applicable) shall be used to determine the most effective temperatures and power (if applicable) for the accelerated electrical endurance test (Subgroup 3B).

### 7.3.3 Subgroup 2B - Radiation Tests

#### 7.3.3.1 *Total Dose Steady-State Radiation Test*

In accordance with ESCC Basic Specification No. [22900](#).

#### 7.3.4 Subgroup 2C - Construction Analysis

##### 7.3.4.1 *Internal Water Vapour Content*

- (a) Applicability  
This test is not applicable to glass devices or to devices without a cavity.
- (b) Procedure  
[MIL-STD-883, Method 1018](#), Procedure 1.

##### 7.3.4.2 *Opening*

The devices shall be opened using a technique which does not contaminate the internal structure or in any way impair the ability to observe defects.

##### 7.3.4.3 *Internal Visual Inspection*

Each device shall be visually inspected in accordance with ESCC Basic Specification No. [20400](#). Photographs shall be taken as follows:

- (a) An overall photograph of the opened device.
- (b) An overall photograph of the die.
- (c) Photographs of any anomalies found.

##### 7.3.4.4 *Scanning Electron Microscope (SEM) Inspection (as applicable)*

This inspection shall include, but shall not necessarily be limited to, examination of the following:

- (a) Detailed examination of any anomalies identified by the internal visual inspection (Para. 7.3.4.3 above). Photographs shall be taken of the above.
- (b) Low magnification (up to 500X) shall be used to assess:
  - (i) Clearance of bond wires at the die edge.
  - (ii) Quality of bonding at the die.
  - (iii) Quality of bonding at the post.Photographs shall be taken of the above.
- (c) High magnification (1000X or greater) shall be used to assess:
  - (i) Metallisation coverage and consistency at steps.
  - (ii) Metallisation coverage at contact windows, bonding pads, etc.Photographs shall be taken of the above.

In the case of devices with a glassivated surface, this examination shall first be attempted through the glassivation.

If the resolution is inadequate, the glassivation shall be removed. This step must be postponed until the bond strength (Para. 7.3.4.5) test has been performed.

##### 7.3.4.5 *Bond Strength Test (if applicable)*

In accordance with Bond Strength in ESCC Generic Specification No. [5000](#).

##### 7.3.4.6 *Die Shear Test (if applicable)*

- (a) Precautions  
If it is known, or believed, that beryllium oxide or other toxic substances are used in the construction of the device, precautionary measures shall be employed.
- (b) Procedure  
In accordance with Die Shear in ESCC Generic Specification No. [5000](#).

#### 7.3.4.7 *Microsectioning*

- (a) Precautions  
As per Para. 7.3.4.6(i) above.
- (b) Glassivation Layer Integrity (if applicable)  
[MIL-STD-883, Method 2021](#).
- (c) Mounting  
The device(s) shall be mounted on a carrier or in a transparent thermosetting resin. This shall have a curing temperature below the maximum storage temperature of the device(s). The resin shall be evacuated after mixing and after the device has been mounted in the uncured resin.
- (d) Microsectioning  
The device(s) shall be ground and polished to achieve a surface finish of at least 0.1 micron. To improve definition and detail, chemical etches shall be used to highlight junction definition, metallographic features, etc. The following, not exhaustive, features shall be assessed:
  - (i) Diffusion and oxide characteristics.
  - (ii) Metal/semiconductor interfaces.
  - (iii) Metal/metal interfaces.
  - (iv) Plating thickness and consistency on posts and pins.

Photographs shall be taken of the above.

#### 7.3.5 Subgroup 2D - Package Tests

##### 7.3.5.1 *General*

The devices in this subgroup shall be divided between Paras. 7.3.5.2, 7.3.5.3 and 7.3.5.4 in the ratio 4:4:2. Any devices from Paras. 7.3.5.2 or 7.3.5.3 that have not been destroyed shall then be subjected to Para. 7.3.5.4.

##### 7.3.5.2 *Thermal Tests*

- (a) Applicability  
These tests must be performed on electrically good devices.
- (b) Procedure
  - (i) Thermal Shock  
All devices shall be subjected to the test defined in ESCC Generic Specification No. [5000](#), 50 cycles instead of 5 cycles. (100 cycles instead of 10 cycles for glass encapsulated devices).
  - (ii) Seal Test  
All devices shall be subjected to the test in accordance with Para. 5.8.
  - (iii) Electrical Measurements  
These measurements shall be made in accordance with Room Temperature Electrical Measurements in the Detail Specification.
  - (iv) Moisture Resistance
    - (a) Applicability  
This test is only applicable to glass non-cavity devices.
    - (b) Procedure  
[MIL-STD-750, Test Method 1021](#).
  - (v) Seal Test  
All devices shall be subjected to the test in accordance with Para. 5.8.
  - (vi) Electrical Measurements  
These measurements shall be made in accordance with Room Temperature Electrical Measurements in the Detail Specification.

### 7.3.5.3 *Mechanical Tests*

- (a) Tests that must be performed on electrically good devices
  - (i) **Mechanical Shock**  
All devices shall be subjected to the test defined in ESCC Generic Specification No. [5000](#), 50 shocks instead of 5 shocks.
  - (ii) **Seal Test**  
All devices shall be subjected to the test in accordance with Para. 5.8.
  - (iii) **Electrical Measurements**  
These measurements shall be made in accordance with Room Temperature Electrical Measurements in the Detail Specification.
  - (iv) **Vibration**  
All devices shall be subjected to the test defined in ESCC Generic Specification No. [5000](#), 120 sweeps (total) instead of 12 sweeps (total).
  - (v) **Seal Test**  
All devices shall be subjected to the test in accordance with Para. 5.8.
  - (vi) **Electrical Measurements**  
These measurements shall be made in accordance with Room Temperature Electrical Measurements in the Detail Specification.
- (b) Tests that can be performed on electrical rejects
  - (i) **Solderability**  
All devices shall be subjected to the test defined in ESCC Generic Specification No. [5000](#).
  - (ii) **Permanence of Marking**  
All devices shall be subjected to the test defined in ESCC Generic Specification No. [5000](#).

### 7.3.5.4 *Resistance to Soldering Heat*

- (a) **Applicability**  
This test must be performed on electrically good devices.
- (b) **Procedure**  
IEC Publication No. 60068-2-20 Test 'Tb', Method '1A' with no thermal screen or flux for  $10 \pm 1s$ , or [MIL-STD-750, Method 2031](#). Following each cycle, electrical measurements shall be performed (go-no-go) in accordance with Room Temperature Electrical Measurements in the Detail Specification and a hermeticity test shall be performed in accordance with Para. 5.8. The test shall be repeated until the device has failed or 5 cycles have been performed, whichever is the sooner.

## 7.3.6 Subgroup 2E - Electrical Tests

### 7.3.6.1 *General*

The components in this subgroup shall be randomly divided between those tests that are performed.

### 7.3.6.2 *Electrostatic Discharge Sensitivity (ESDS) Test*

ESD testing shall be performed in accordance with ESCC Basic Specification No. [23800](#). If the component under examination is not categorised into one of the 3 classes listed, then the component shall be termed "unclassified".

7.3.6.3 *Characterisation*

(a) Safe Operating Area

(i) Applicability

This test is only applicable to devices where operation in circuits requiring transfer and dissipation of significant and/or varying levels of power is an intended feature of their design. The ESCC Executive shall review the component type and technology to determine the applicability of the test.

(ii) Procedure

[MIL-STD-750, Method 3051, 3052, 3053, or 3474](#) as applicable.

(b) Current Limits

The design of each device under investigation shall be examined to ensure that no part of the device carries more than the maximum current defined by the technology or process design rules.

(c) Breakdown Voltage

[MIL-STD-750, Method 3001, 3011, 3026, 3401, 3403, 3407, 4021, or 4022](#) as applicable.

7.4 GROUP 3 - ENDURANCE TESTS

7.4.1 General

This group shall be randomly divided into 3 subgroups in the proportions indicated in Chart I.

7.4.2 Subgroup 3A - High Temperature Reverse Bias (HTRB) Test

Unless otherwise specified in the Detail Specification, all devices shall be subjected to the test defined in ESCC Generic Specification No. [5000](#).

7.4.3 Subgroup 3B - Accelerated Electrical Endurance Test

This group shall be randomly divided into 3 subgroups in the proportions indicated in Chart I. The applicable tests shall not be performed until the subgroup 2A tests have been completed and analysed, and 3 test conditions selected. The tests in this group shall be performed as specified in Chart IV.

The temperatures  $T_1$ ,  $T_2$  and  $T_3$  shall be chosen such that within approximately 1000, 500 and 168 hours, the parameter(s) defined in Para. 7.3.2.3 above can be expected to have drifted to an extreme of the permitted range. A common applied power (if applicable) also determined from the Subgroup 2A tests, shall be used. If the power step-stress test was not performed, the devices shall be operated at their maximum rated dissipation. Intermediate electrical measurements shall be performed in accordance with Para. 7.3.2.3 above at the following times:

$T_1$ (1000hrs)	$T_2$ (500hrs)	$T_3$ (168hrs)
168 (+24 -0)hrs	168 (+ 24 -0)hrs	168 (+ 24 -0)hrs
500 (+ 24 -0)hrs	500 (+ 24 -0)hrs	-
1000 (+ 24 -0)hrs	-	-

Failed components shall be removed for analysis as specified in Para. 7.1.

7.4.4 Subgroup 3C - Extended Burn-in Test

The devices shall be tested for 1000 hours at the conditions defined in the Detail Specification for burn-in. Intermediate electrical measurements shall be performed in accordance with Para. 7.3.2.3 above at the following times: 168 (+24 -0)hrs, 500 (+24 -0)hrs and 1000 (+24 -0)hrs. If the conditions determined for the 1000 hour subgroup in 7.4.3 above are identical to those defined for burn-in, this test shall not be performed.

7.5 GROUP 4 - RESERVE

Should any additional tests be considered necessary, the devices in this subgroup shall be used.

## **8 DATA DOCUMENTATION**

### **8.1 GENERAL REQUIREMENTS**

An evaluation test report shall be established. This shall comprise the following:

- (a) Cover sheet (or sheets).
- (b) List of equipment (testing and measuring).
- (c) List of test references.
- (d) Sample identification.
- (e) Production data.
- (f) Inspection data.
- (g) Initial electrical measurements.
- (h) Group 1 - Control Group data.
- (i) Thermal Resistance/Conductivity data.
- (j) Subgroup 2A(i) - Temperature Step-Stress test data (if applicable).
- (k) Subgroup 2A(ii) - Power Step-Stress test data (if applicable).
- (l) Subgroup 2A(iii) - Intermittent Operating Life Test (if applicable).
- (m) Subgroup 2B - Radiation tests data.
- (n) Subgroup 2C - Construction Analysis data.
- (o) Subgroup 2D - Package tests data.
- (p) Subgroup 2E - Electrical tests data.
- (q) Subgroup 3A - High Temperature Reverse Bias (HTRB) test data (if applicable).
- (r) Subgroup 3B - Accelerated Electrical Endurance test data.
- (s) Subgroup 3C - Extended Burn-in test data.
- (t) Group 4 - Reserve data (if applicable).
- (u) Summary of results and conclusions.

Items (a) to (u) inclusive shall be grouped, preferably as subpackages, and for identification purposes, each page shall include the following information:

- Manufacturer's/test house's name.
- Lot identification.
- Date of establishment of the document.
- Page number.

### **8.2 COVER SHEET(S)**

The cover sheet (or sheets) of the evaluation test report shall include as a minimum:

- (a) Reference to this document, including issue and date.
- (b) Component type and number.
- (c) Lot identification.
- (d) Manufacturer's/test house's name and address.
- (e) Location of the manufacturing plant/test house.
- (f) Signature on behalf of the Manufacturer/test house.
- (g) Total number of pages of the evaluation test report.

### **8.3 LIST OF EQUIPMENT USED**

A list of equipment used for tests and measurements shall be included in the evaluation test report. Where applicable, this list shall contain the inventory number, Manufacturer type number, serial number, calibration status data, etc. This list shall indicate for which tests such equipment was used.

- 8.4 LIST OF TEST REFERENCES  
This list shall include all references or codes which are necessary to correlate the test data provided with the applicable tests.
- 8.5 SAMPLE IDENTIFICATION (PARA. 4.1)  
This shall identify the criteria used for the selection of the particular components used for the tests, when evaluating a range of components by means of representative samples.
- 8.6 PRODUCTION DATA (PARA. 4.4)  
The progress of the components through the normal manufacturing processes shall be documented. The components failing a particular process shall be detailed, together with the reason for their removal.
- 8.7 INSPECTION DATA (PARA. 5)  
The number of components subjected to each test shall be identified together with the number and reason for any rejects. Radiographs (if applicable) of any failed components shall be presented.
- 8.8 INITIAL ELECTRICAL MEASUREMENTS (PARA. 6)  
All data shall be recorded against serial numbers. A histogram of device parameters shall be produced.
- 8.9 GROUP 1 - CONTROL GROUP DATA (PARA. 7.2)  
All data shall be recorded against serial numbers.
- 8.10 SUBGROUP 2A - STEP-STRESS TESTS DATA
- 8.10.1 Thermal Resistance/Conductivity Data (Para. 7.3.2.2)  
All data shall be recorded against serial numbers.
- 8.10.2 Subgroup 2A(i) - Temperature Step-Stress Test Data (Para. 7.3.2.4) (if applicable)  
All data shall be recorded against serial numbers. This shall include:
- (a) Starting temperature.
  - (b) Temperature steps.
  - (c) Electrical measurements tabulated for each step.
  - (d) Graphical output as defined in Para. 7.3.2.7.
  - (e) Analysis of any failed components as defined in Para. 7.1.
  - (f) Thermal resistance/conductivity measurements from surviving devices.
- 8.10.3 Subgroup 2A(ii) - Power Step-Stress Test Data (Para. 7.3.2.5) (if applicable)  
All data shall be recorded against serial numbers. This shall include:
- (a) Starting power.
  - (b) Power steps.
  - (c) Electrical measurements tabulated for each step.
  - (d) Graphical output as defined in Para. 7.3.2.7.
  - (e) Analysis of any failed components as defined in Para. 7.1.
  - (f) Thermal resistance/conductivity measurements from surviving devices.

- 8.10.4 Subgroup 2A(iii) - Intermittent Operating Life Test Data (Para. 7.3.2.6) (if applicable)  
All data shall be recorded against serial numbers. This shall include:
- (a) Applied power and temperature conditions.
  - (b) Electrical measurements as defined in Para. 7.3.2.3.
  - (c) Graphical output as defined in Para. 7.3.2.7.
  - (d) Analysis of any failed components as defined in Para. 7.1.
  - (e) Thermal resistance/conductivity measurements from surviving devices.
- 8.11 SUBGROUP 2B - RADIATION TESTS DATA (PARA. 7.3.3)  
All data shall be recorded against serial numbers. This shall include:
- (a) Total dose steady-state test data.
  - (b) Single Event Phenomena test data (if applicable).
- 8.12 SUBGROUP 2C - CONSTRUCTION ANALYSIS DATA (PARA. 7.3.4)  
All data shall be recorded against serial numbers. This shall include:
- (a) Internal water vapour content data.
  - (b) Photographs.
  - (c) SEM photographs.
  - (d) Results of bond strength test.
  - (e) Results of die shear test.
  - (f) Glassivation layer integrity test data (if applicable).
  - (g) Microsectioning photographs.
- 8.13 SUBGROUP 2D - PACKAGE TESTS DATA (PARA. 7.3.5)  
All data shall be recorded against serial numbers. This shall include:
- (a) Thermal tests data.
  - (b) Mechanical tests data.
  - (c) Resistance to soldering heat test data.
- 8.14 SUBGROUP 2E - ELECTRICAL TESTS DATA (PARA. 7.3.6)  
All data shall be recorded against serial numbers. This shall include:
- (a) ESDS test data.
  - (b) Characterisation data.
- 8.15 GROUP 3 - ENDURANCE TESTS DATA
- 8.15.1 Subgroup 3A - High Temperature Reverse Bias (HTRB) Test Data (Para. 7.4.2) (if applicable)  
All data shall be recorded against serial numbers.

8.15.2 Subgroup 3B - Accelerated Electrical Endurance Test Data (Para.7.4.3)

All data shall be recorded against serial numbers. This shall include:

- (a) Temperatures  $T_1$ ,  $T_2$  and  $T_3$  chosen.
- (b) Power chosen (if applicable).
- (c) Electrical measurements tabulated and plotted for each intermediate time as defined in Para. 7.4.3.
- (d) Drift values referred to the initial electrical measurements (Para. 6).
- (e) Analysis of any failed components as defined in Para. 7.1.

8.15.3 Subgroup 3C - Extended Burn-in Test Data (Para. 7.4.4)

All data shall be recorded against serial numbers.

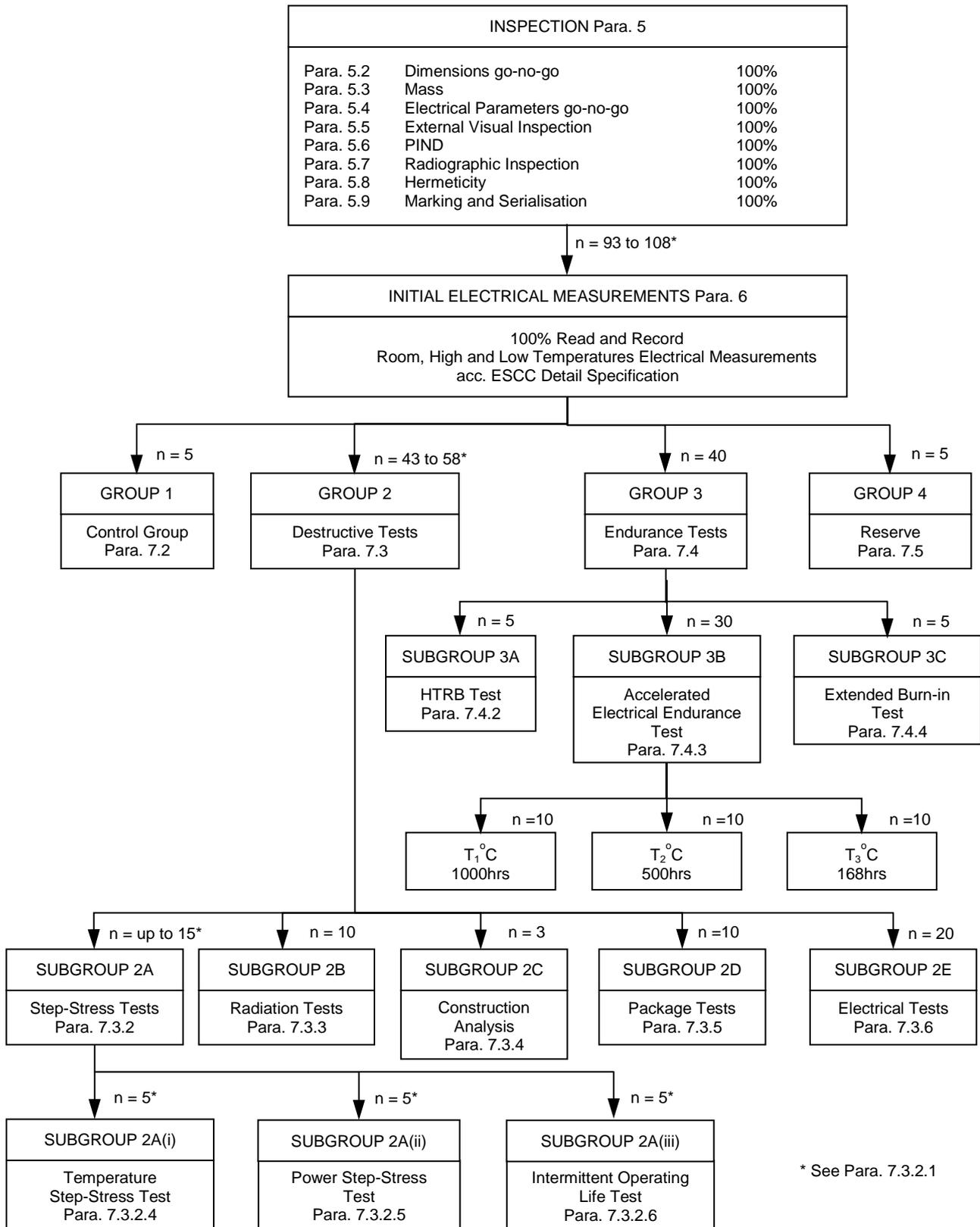
8.16 GROUP 4 - RESERVE DATA (PARA. 7.5) (IF APPLICABLE)

All data shall be recorded against serial numbers.

8.17 SUMMARY OF RESULTS AND CONCLUSIONS

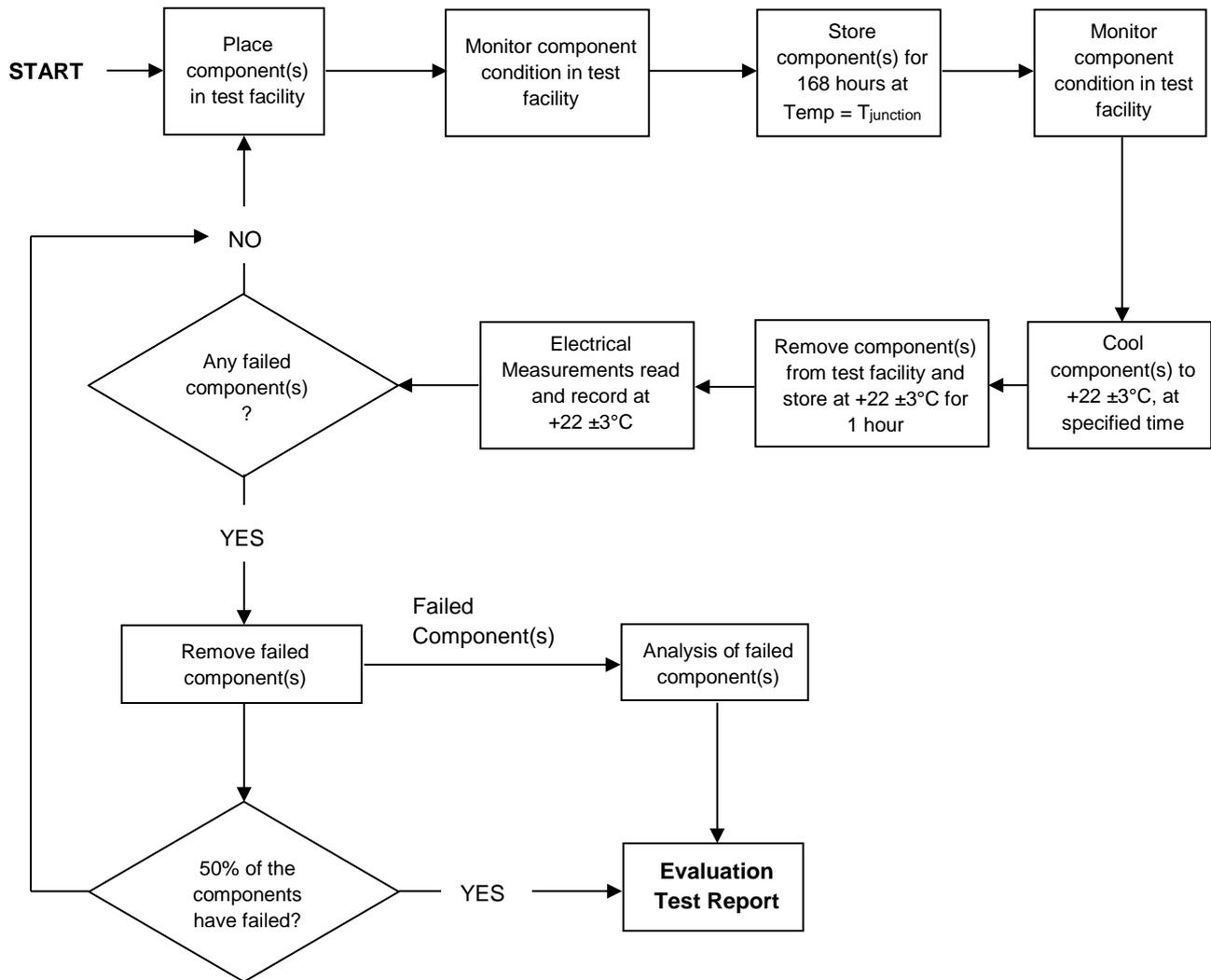
The above shall be briefly reviewed, indicating the success or otherwise of the evaluation test programme. Any production screens that need to be introduced into the PID shall be outlined.

**CHART I – EVALUATION TEST PROGRAMME**



\* See Para. 7.3.2.1

**CHART II – TEMPERATURE STEP-STRESS SEQUENCE**



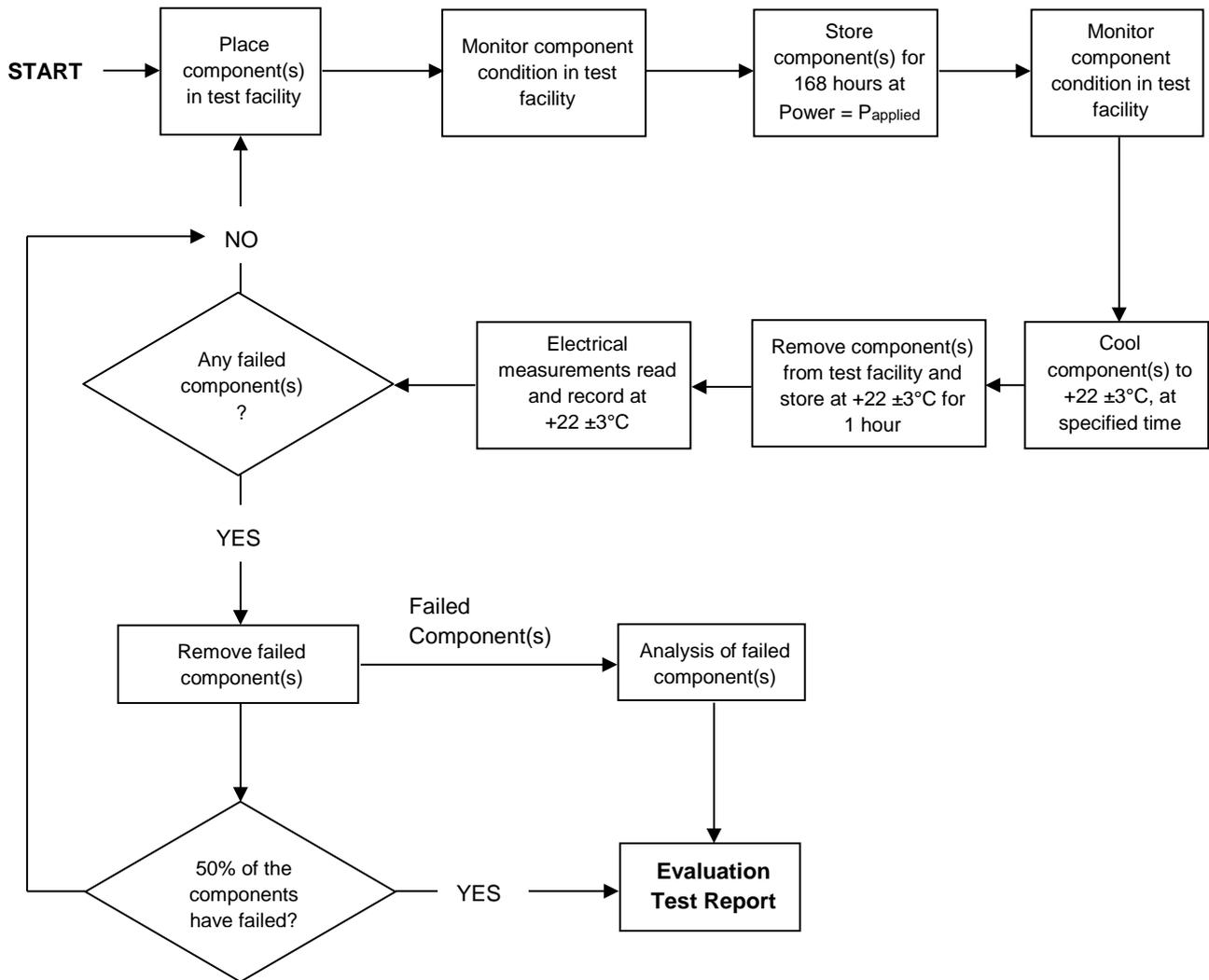
**NOTES:**

1. Temperature steps with  $T_{junction}$ :

- First step:  $T_0$  (°C)
- $T_1$  (°C)
- $T_2$  (°C)
- Last step:  $T_n$  (°C)

with  $(T_n > \dots T_2 > T_1 > T_0)$

**CHART III – POWER STEP-STRESS SEQUENCE**



**NOTES:**

1. Power steps with  $P_{applied}$ :
 

First step:	$P_0$	(W)
	$P_1$	(W)
	$P_2$	(W)
Last step:	$P_n$	(W)

with  $(P_n > \dots P_2 > P_1 > P_0)$

**CHART IV - ACCELERATED ELECTRICAL ENDURANCE TEST**
